PCN Number:			20240520008.1					CN Date:	May 23, 2024
Title:	Datasheet for	, ,					•		
Customer Contact:		Change Management team Dept:						Quality Services	
Propos	ed 1 st Ship Da	te:	Augu	st 2:	1, 2024			_	
Change	Туре:		•						
Ass	embly Site		Design			Wafer Bump Material			
Assembly Process			X	Data Sheet			Wafer Bump Process		
Assembly Materials			Part number change			Wafer Fab Site			
Med	chanical Specifi	cation Test Site				Wafer Fab			
Packing/Shipping/Labeling				Test Process			Wafer Fab Process		
HE HOHE						arized below	•		
Jia Te	wing change h							OPA130, OPA 2 53B – MAY 1998 – F	2130, OPA4130 REVISED MAY 2024
TE IN	owing change h EXAS ESTRUMENTS ES from Revision	istory A (Ma	rch 2006	des f	urther details Revision B (May	2024)	SBOS0	53B – MAY 1998 – F	Page
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The datasheet number will be changing.

Device Family

Change From:

Change To:

SBOS053B

SBOS053B

These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/OPA130

Reason for Change:

Supply Continuity

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

These changes are part of our multiyear plan to transition products from our 150-millimeter factories to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity. Datasheet changes associated with PCN 20240202010

Changes to product identification resulting from this PCN:									
None.									
Product Affected:									
OPA130UA	OPA130UA/2K5	OPA2130UA	OPA2130UA/2K5						
OPA4130UA	OPA4130UA/2K5								

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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